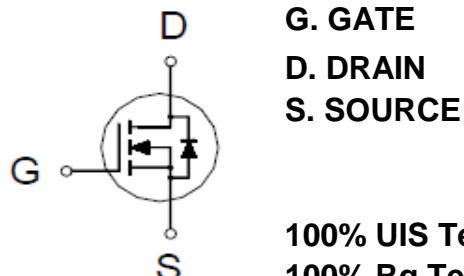


PE800BA

N-Channel Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
30V	5.7mΩ @ $V_{GS} = 10V$	49A



G. GATE
D. DRAIN
S. SOURCE

100% UIS Tested
100% Rg Tested

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current ⁴	$T_C = 25^\circ C$	I_D	49	A
	$T_C = 100^\circ C$		31	
Continuous Drain Current ⁴	$T_A = 25^\circ C$		19	
	$T_A = 70^\circ C$		15	
Pulsed Drain Current ¹		I_{DM}	82	
Avalanche Current		I_{AS}	24	
Avalanche Energy	$L = 0.1mH$	E_{AS}	30	mJ
Power Dissipation	$T_C = 25^\circ C$	P_D	24	W
	$T_C = 100^\circ C$		9	
Power Dissipation ³	$T_A = 25^\circ C$		3.1	
	$T_A = 70^\circ C$		2	
Operating Junction & Storage Temperature Range		T_J, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE		SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient ²	$t \leq 10s$	$R_{\theta JA}$	$R_{\theta JA}$	40	°C / W
Junction-to-Ambient ²	Steady-State	$R_{\theta JA}$		85	
Junction-to-Case	Steady-State	$R_{\theta JC}$		5.3	

¹Pulse width limited by maximum junction temperature.

²The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ C$.

³The Power dissipation is based on $R_{\theta JA}$ $t \leq 10s$ value.

⁴Package limitation current is 20A.

PE800BA

N-Channel Enhancement Mode MOSFET

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.3	1.9	2.3	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 24\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
		$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 55^\circ\text{C}$			10	
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 13\text{A}$		6.8	8.8	$\text{m}\Omega$
		$V_{\text{GS}} = 10\text{V}, I_D = 13\text{A}$		4.4	5.7	
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = 5\text{V}, I_D = 13\text{A}$		85		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 15\text{V}, f = 1\text{MHz}$		1115		pF
Output Capacitance	C_{oss}			537		
Reverse Transfer Capacitance	C_{rss}			33		
Gate Resistance	R_g	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0\text{V}, f = 1\text{MHz}$		1.5		Ω
Total Gate Charge ²	$Q_g(V_{\text{GS}}=10\text{V})$	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 13\text{A}$		21		nC
	$Q_g(V_{\text{GS}}=4.5\text{V})$			11		
Gate-Source Charge ²	Q_{gs}			3		
Gate-Drain Charge ²	Q_{gd}			5		
Turn-On Delay Time ²	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = 15\text{V}, I_D \geq 13\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		14		nS
Rise Time ²	t_r			66		
Turn-Off Delay Time ²	$t_{\text{d}(\text{off})}$			35		
Fall Time ²	t_f			49		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ\text{C}$)						
Continuous Current ³	I_S				20	A
Forward Voltage ¹	V_{SD}	$I_F = 13\text{A}, V_{\text{GS}} = 0\text{V}$			1.2	V
Reverse Recovery Time	t_{rr}	$I_F = 13\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$		31		nS
Reverse Recovery Charge	Q_{rr}			16		nC

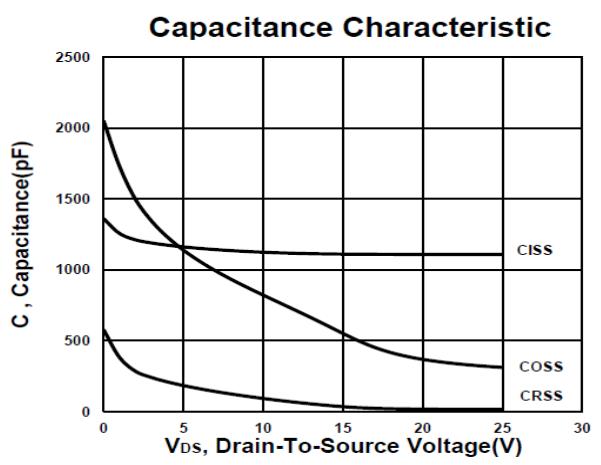
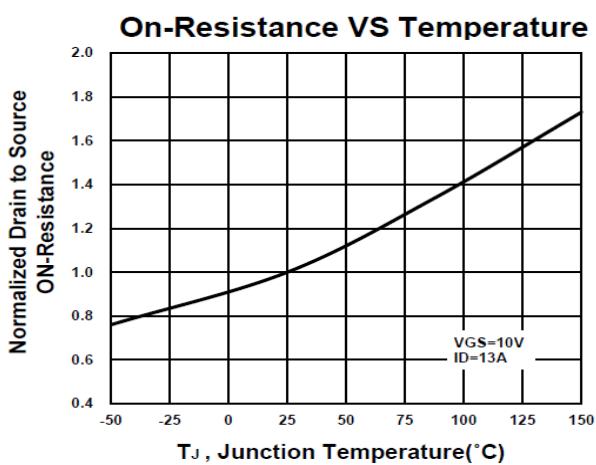
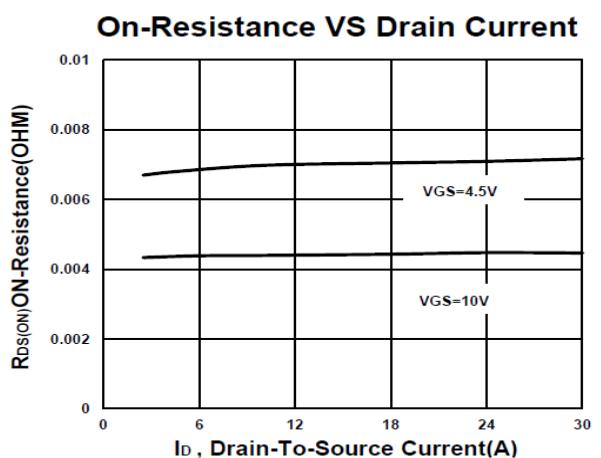
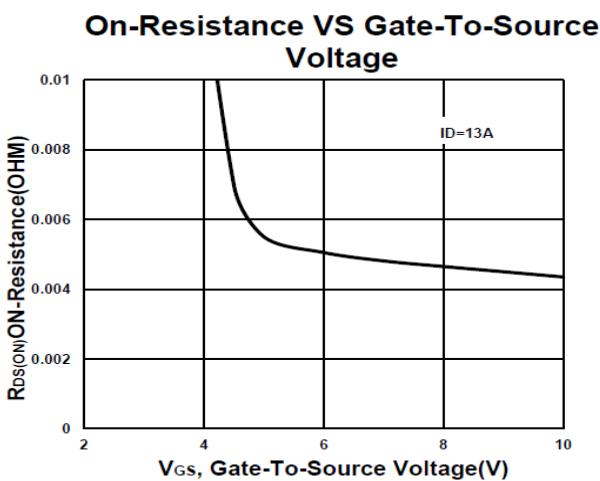
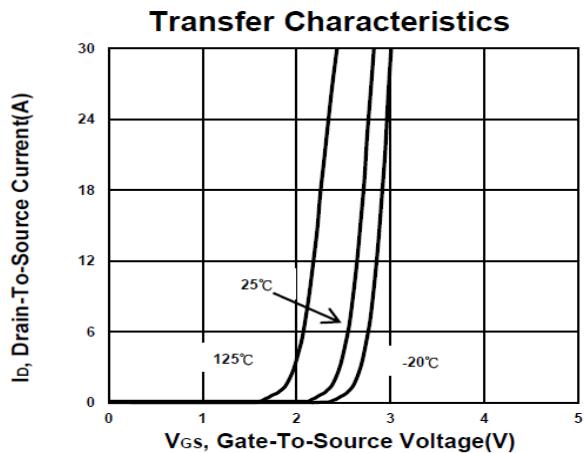
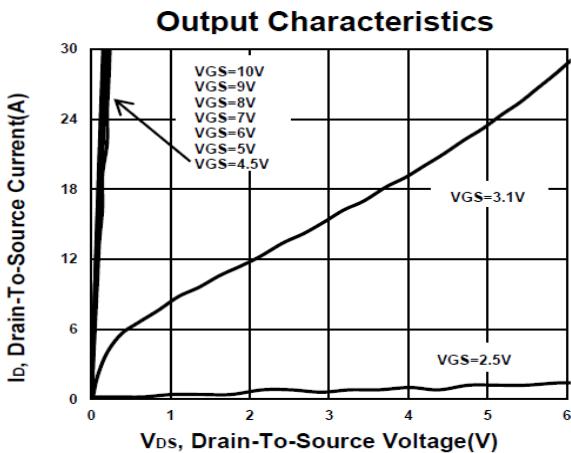
¹Pulse test : Pulse Width $\leq 300\ \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

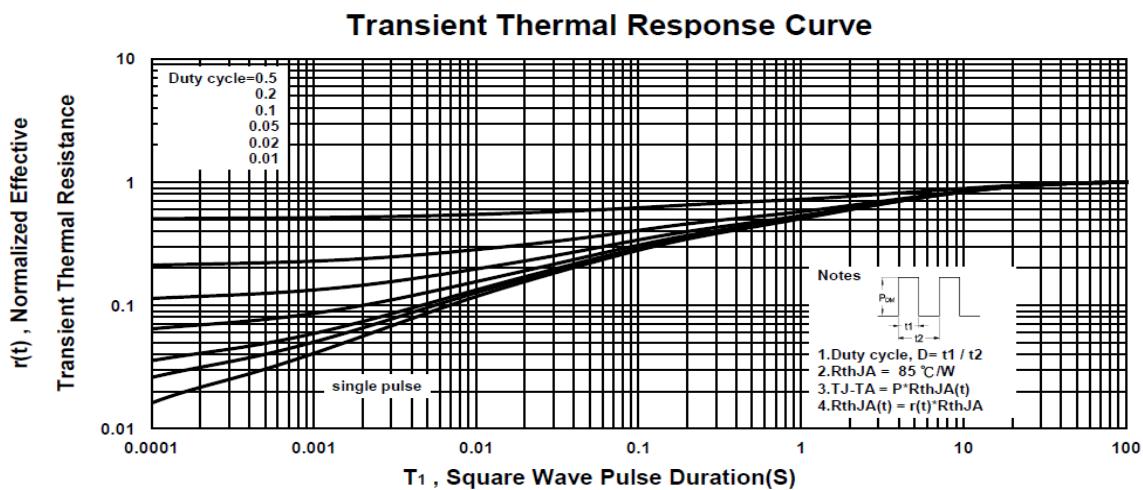
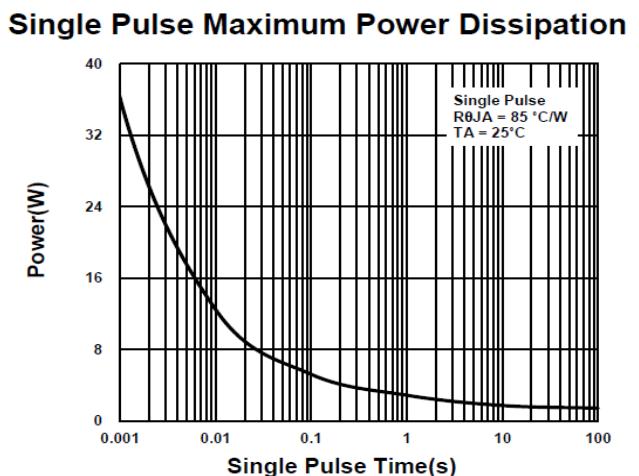
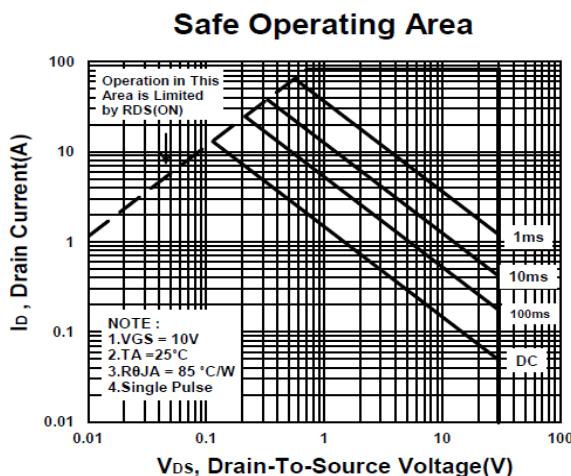
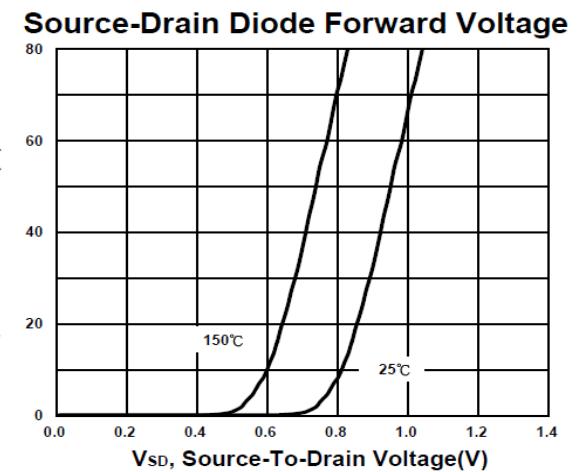
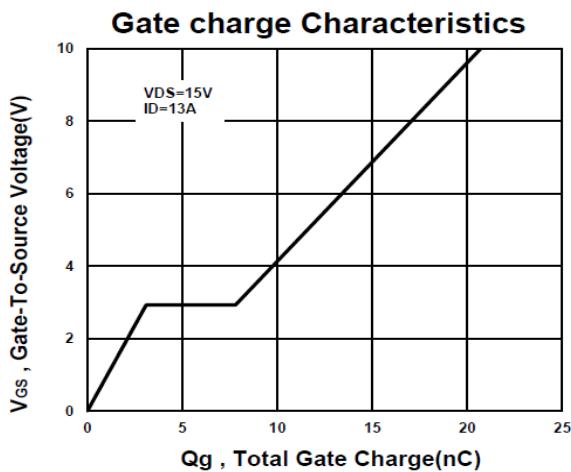
³Package limitation current is 20A.

PE800BA

N-Channel Enhancement Mode MOSFET

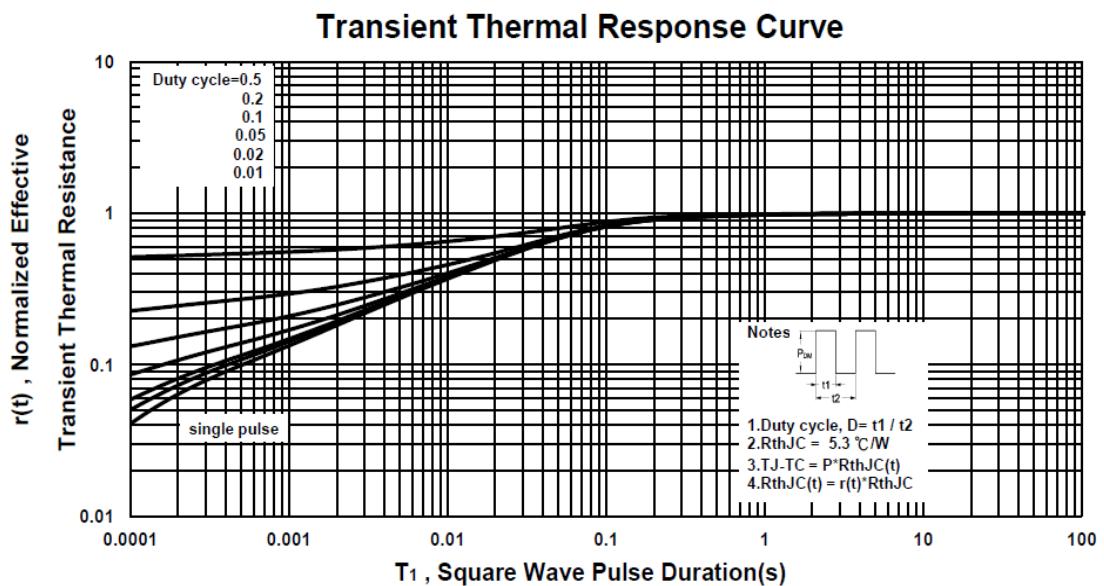
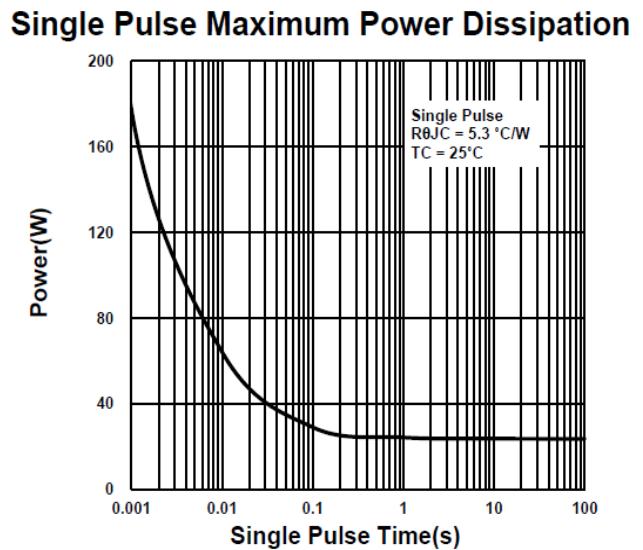
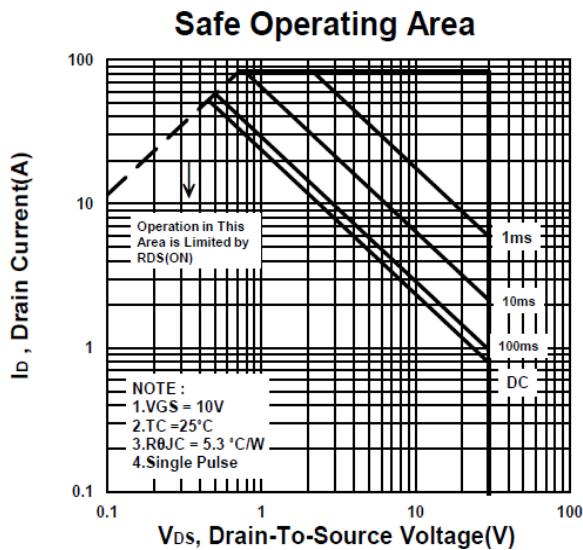


PE800BA N-Channel Enhancement Mode MOSFET



PE800BA

N-Channel Enhancement Mode MOSFET



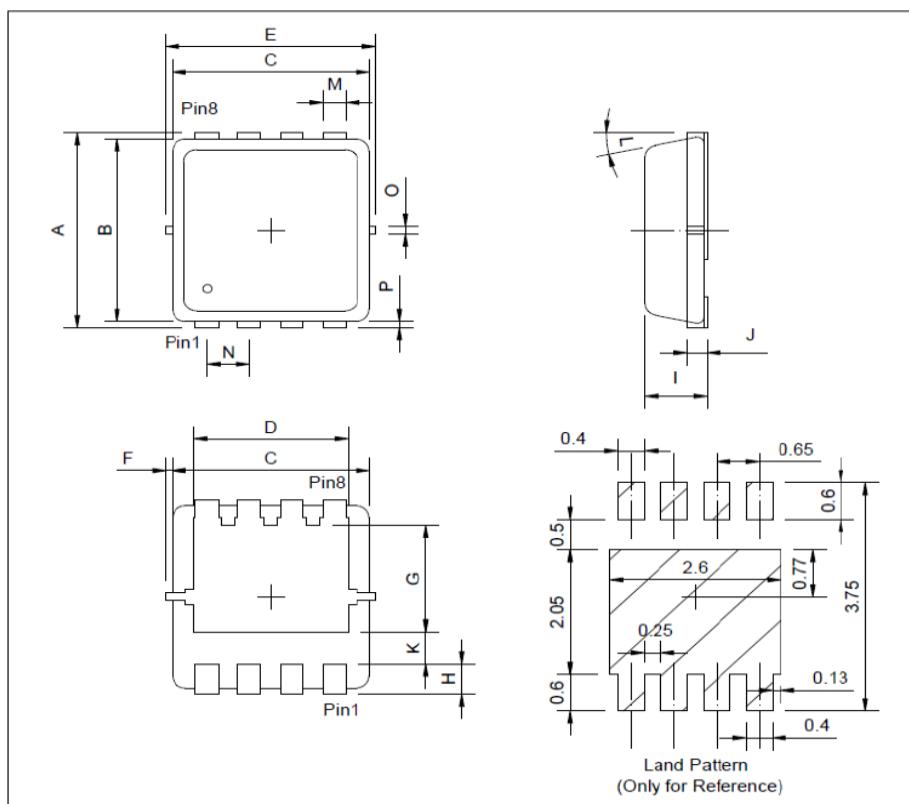
PE800BA

N-Channel Enhancement Mode MOSFET

Package Dimension

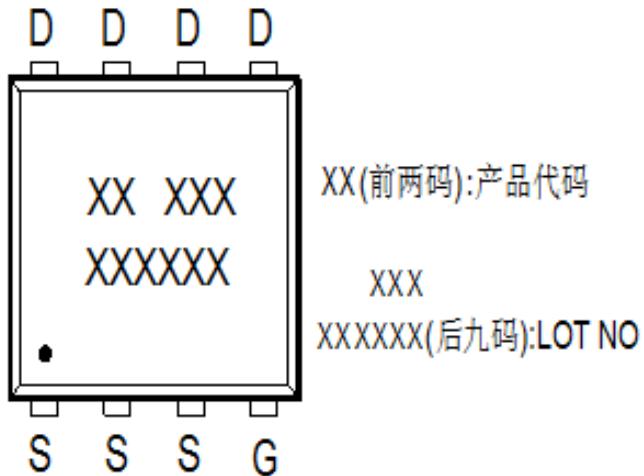
PDFN 3x3P MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	3	3.3	3.6	I	0.65	0.8	0.9
B	2.88	3	3.2	J	0.1	0.15	0.25
C	2.9	3	3.25	K	0.59		
D	2.29	2.45	2.69	L	0°	10°	12°
E	3	3.3	3.6	M	0.14	0.3	0.4
F	0	0.1	0.2	N	0.55	0.65	0.75
G	1.35	1.75	2.2	O		0.2	
H	0.15	0.3	0.55	P	0		0.2

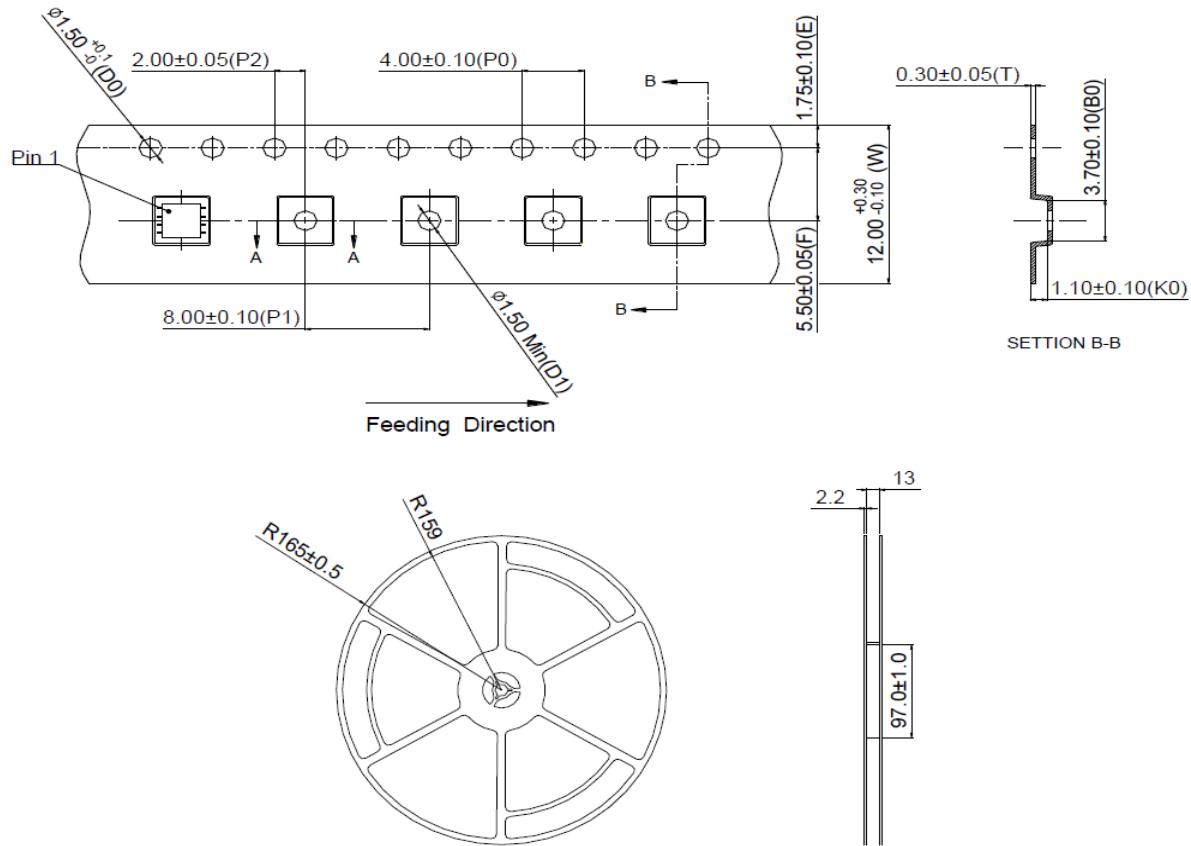


PE800BA N-Channel Enhancement Mode MOSFET

A. Marking Information(此产品代码为: P7)



B. Tape&Reel Information:5000pcs/Reel

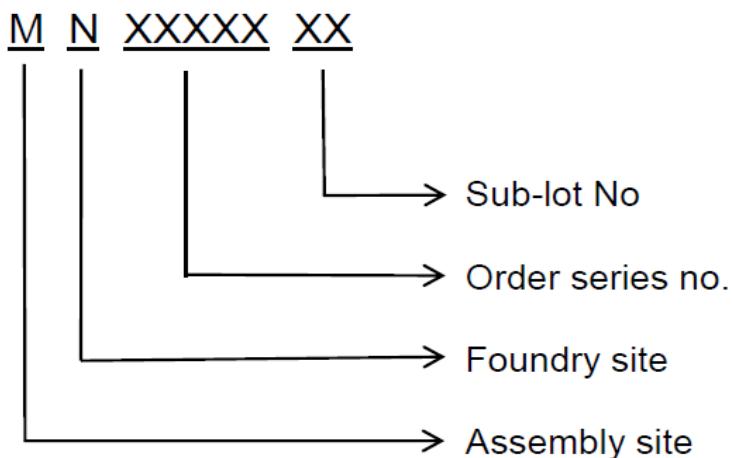


PE800BA

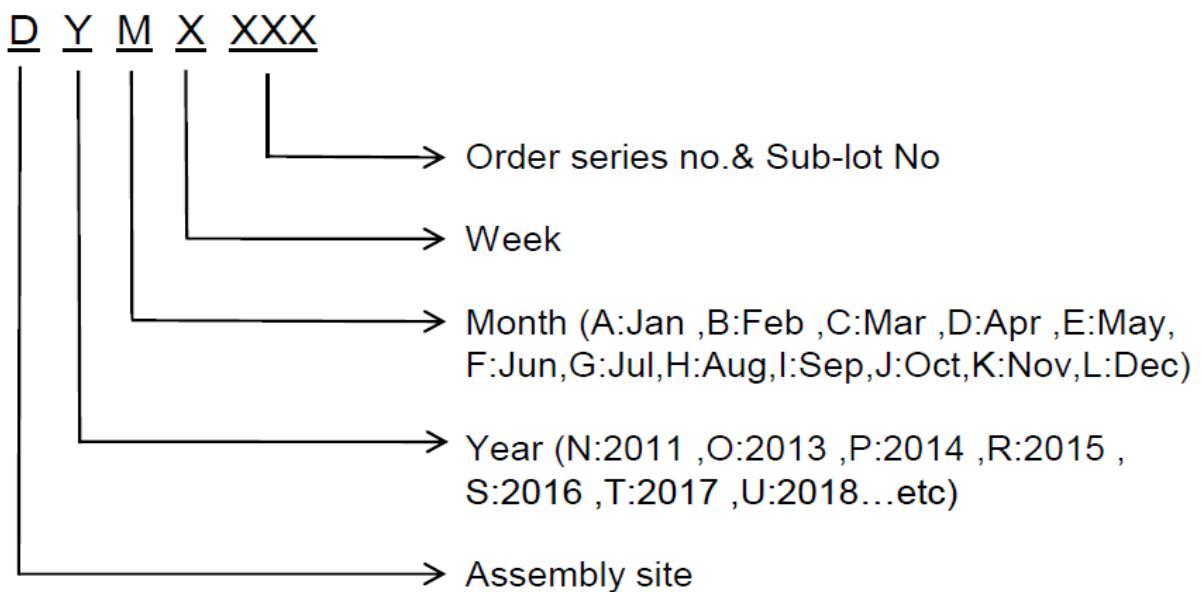
N-Channel Enhancement Mode MOSFET

C. Lot No.&Date Code rule

1.Lot No.



2.Date Code



PE800BA N-Channel Enhancement Mode MOSFET

D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm			
2	Font style	Times New Roman or Arial (或可区分英文“0”和数字“0”，“G”和“Q”的字型即可)			
3	U-NIKC	Height: 4 mm			
4	Package	Height: 2 mm			
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12			
6	Device	Height: 3 mm (Max: 16 Digit)			
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot			
8	D/C	Height: 3 mm (Max: 7 Digit)			
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed			
10	RoHS label	RoHS long axis: 12 mm minor axis: 6 mm bottom color: White Font color: Black Font style: Arial			
11	Halogen Free label	G Diameter: 10 mm bottom color: Green Font color: Black Font style: Arial			
12	Scan information	Device / Lot / D/C / QTY , Insert “ / “ between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least			